

# APPLICATION NOTE

# Entegris Waffle Trays

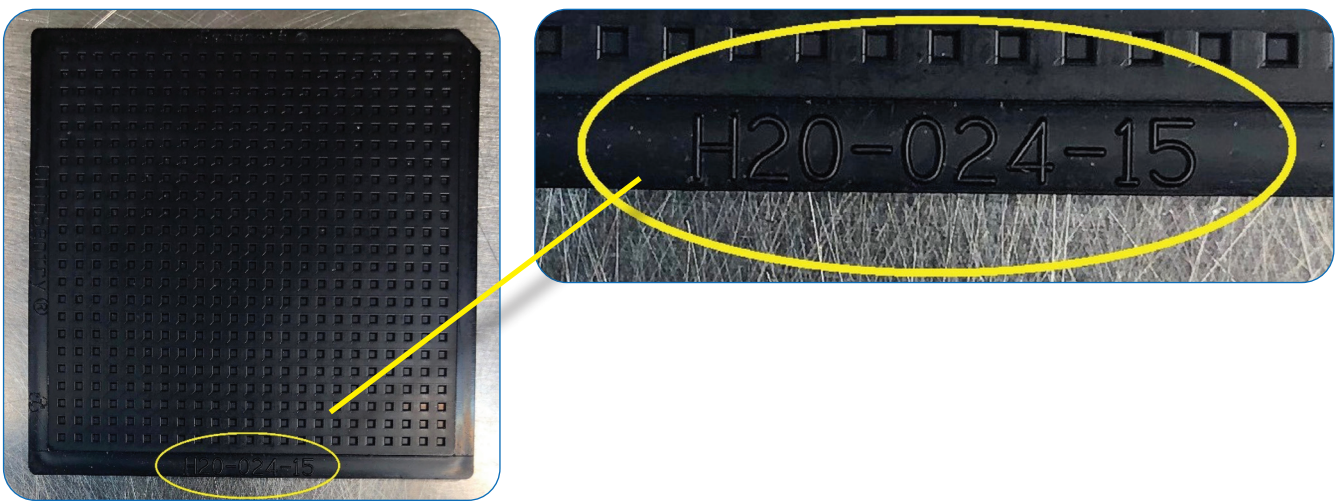
## Finding Dimensions and Other Specifications

### Introduction

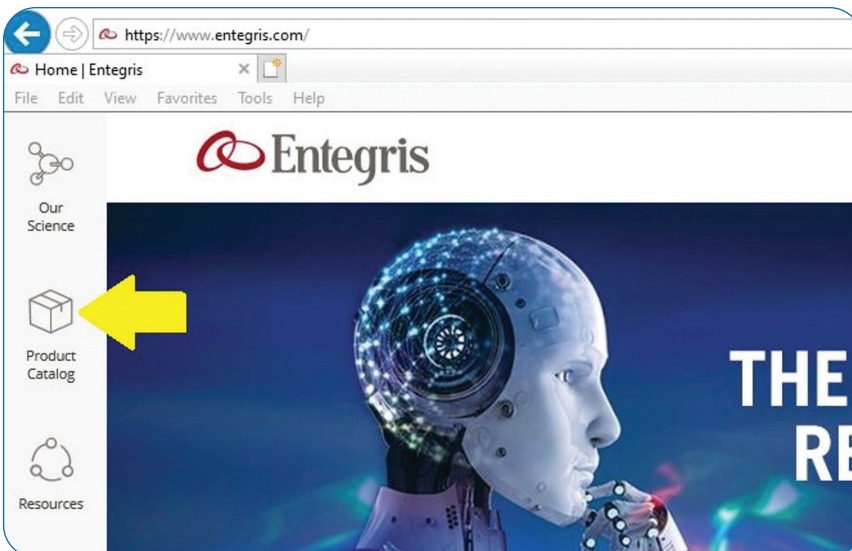
Entegris is a leading global supplier of waffle trays used in the packaging of solder preforms—typically AuSn preforms—as well as other materials and devices, such as semiconductor die.

All the information for specific Entegris waffle trays is generally readily and publicly available on the Entegris website, [www.entegris.com](http://www.entegris.com)

The Entegris part number is embossed on the waffle tray. This is the part number that you will need to research the waffle tray.



Once you have located the Entegris part number, go to the website ([www.entegris.com](http://www.entegris.com)) and click on Product Catalog.



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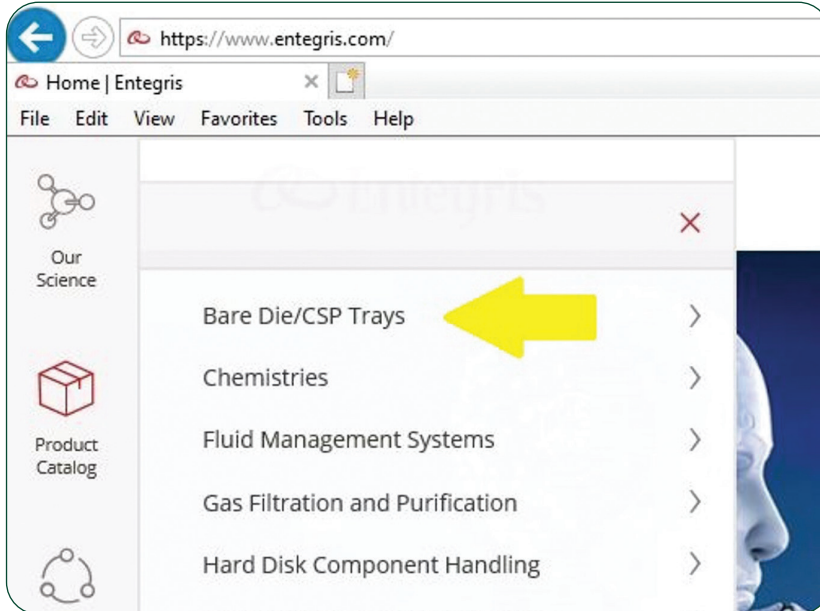


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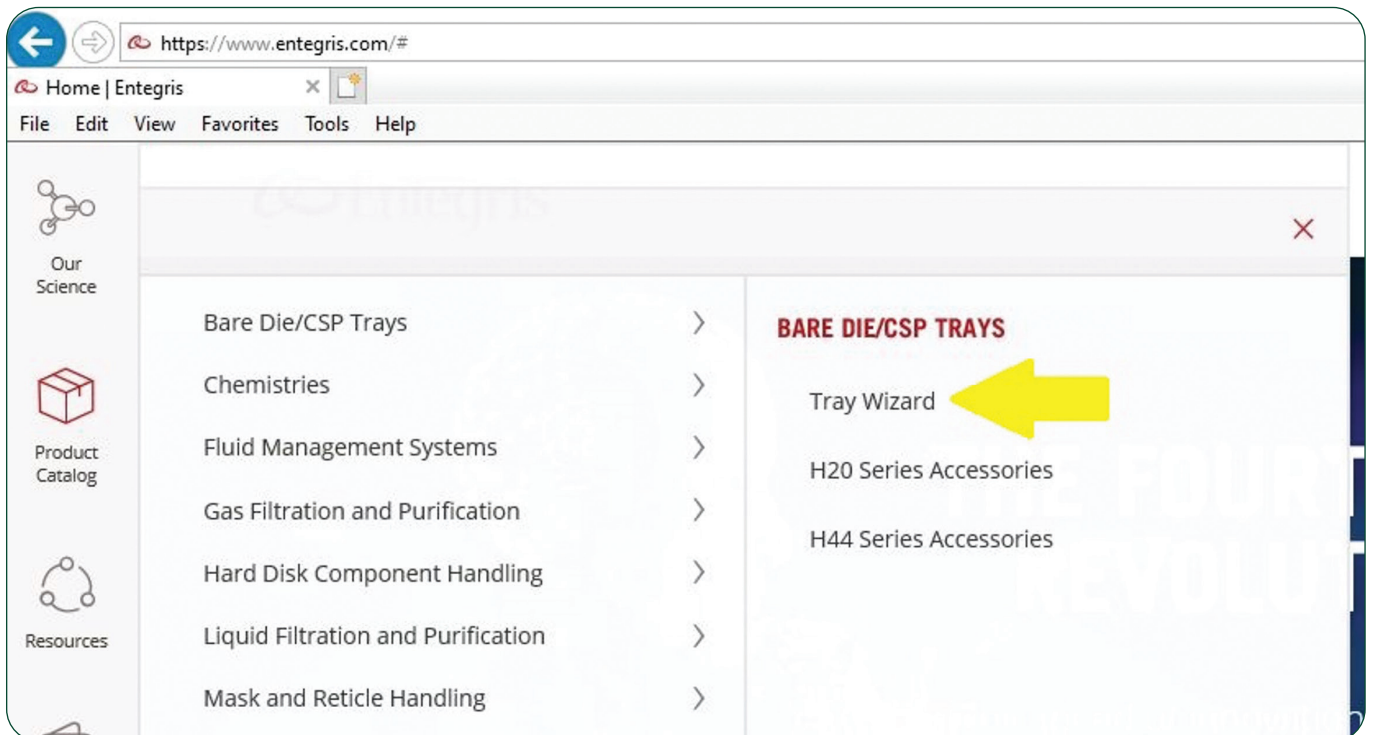
# Entegris Waffle Trays

## Finding Dimensions and Other Specifications

Click on Bare Die/CSP Trays.



Click on Tray Wizard.



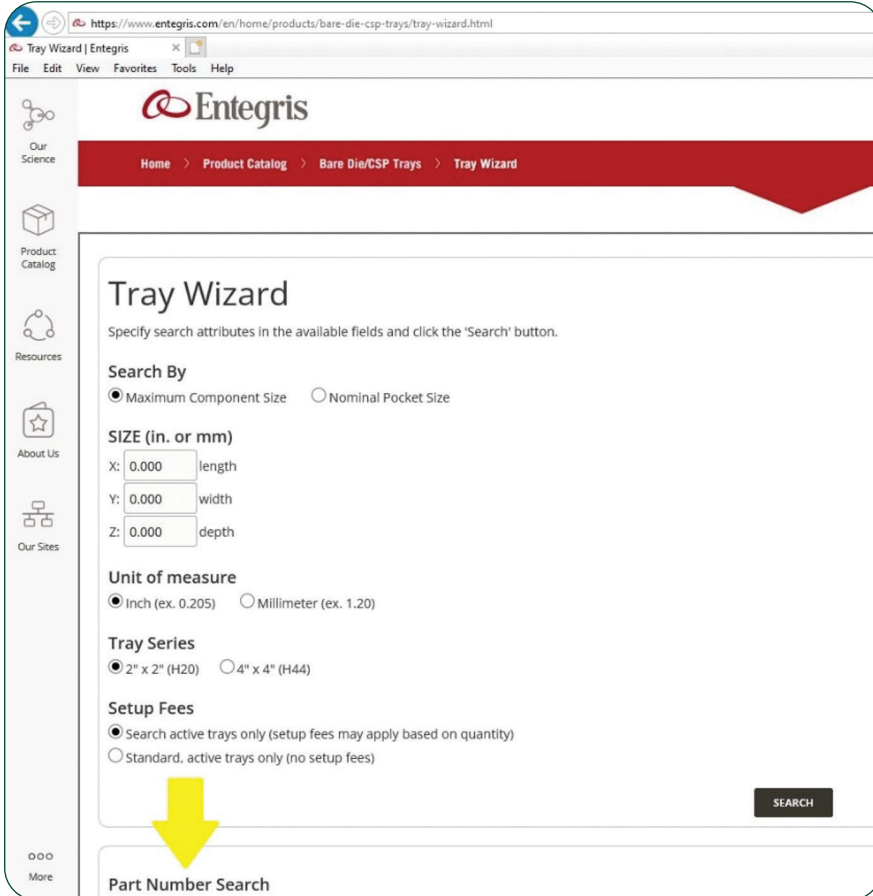


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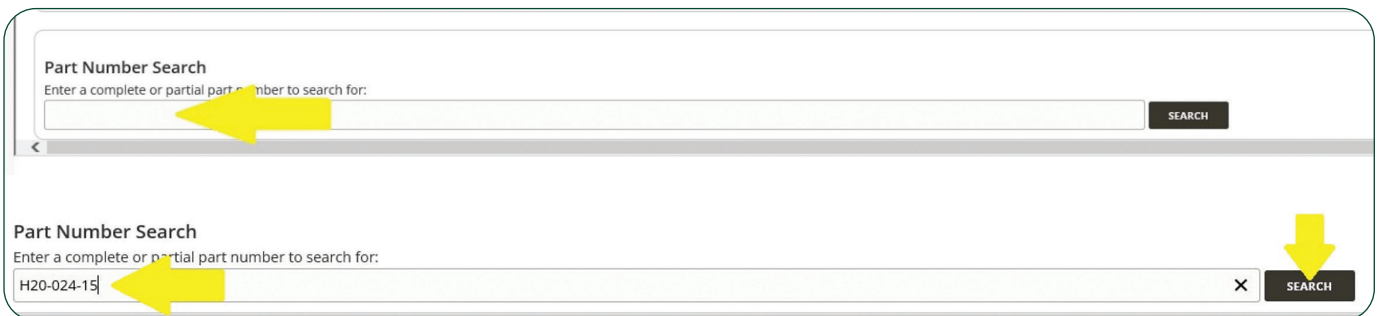
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## Finding Dimensions and Other Specifications

Scroll down to Part Number Search.



Enter the Entegris part number and click on Search.



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## Finding Dimensions and Other Specifications

Sometimes, more than one option will be found. This is because Entegris may have more than one option for the waffle tray material, even though the dimensions of the tray will be identical. The suffix of the part number indicates the waffle tray material. However, the suffix is not always embossed on the waffle tray.

Search: H20-024-15

Results 1-2 of 2 matching record(s).

Part Number	Description
H20-024-15-62C02	<b>H20 Series Bare Die/CSP Tray</b> STAT-PRO® 150 (Black Conductive Polypropylene) Pocket Dimensions: 0.024" x 0.024" x 0.015" Capacity: 23x23 (529)
H20-024-15-66C02	<b>H20 Series Bare Die/CSP Tray</b> ChipSentry® (Black Conductive Polycarbonate) Pocket Dimensions: 0.024" x 0.024" x 0.015" Capacity: 23x23 (529)

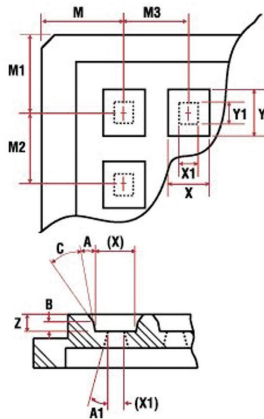
The material of the waffle tray is also embossed on the waffle tray, just like the part number is. In this case, it is ChipSentry®, which corresponds to the part number with the 66C02 suffix. Click on the correct part number.

This will take you to the page on the website that shows the dimensions of the waffle tray.



### H20-024-15-66C02 Bare Die / CSP Tray Detail

#### Dimensions



Note: Image displayed is not an exact representation of the actual product. Part tolerances may differ from the information displayed above. Please contact Customer Service for a complete technical drawing.

#### Pocket Locations

M = 0.164" ±0.003"  
M1 = 0.164" ±0.003"  
M2 = 0.076" ±0.002"  
M3 = 0.076" ±0.002"  
Array = 23x23 (529)

#### Pocket Details

X = 0.024 pocket size  
Y = 0.024 pocket size  
Z = 0.015 pocket depth  
Contact Technical Customer Service for pocket tolerances  
A = 5° ±1/2° pocket draft angle  
No Cross Slots

#### Overall Tray Size

Size = 2.000" ±0.004"  
Height = 0.156" +0.002" -0.003"  
Flatness = 0.004"  
Note = EDM FINISH ON BACK SIDE OF TRAY

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All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.  
Indium Corporation is an ISO 9001:2015 registered company.



Contact our engineers: [askus@indium.com](mailto:askus@indium.com)

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